

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3233360

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAMEER S. VADHAVKAR	02/18/2015
XIAO LI	02/18/2015
ANILKUMAR CHANDOLU	02/18/2015
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716-9632
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14626575
CORRESPONDENCE DATA	
Fax Number:	(209)299-9288
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	206-903-8757
Email:	ip.docket.se@dorsey.com
Correspondent Name:	DORSEY & WHITNEY LLP-IP DEPT.-MTI
Address Line 1:	COLUMBIA CENTER
Address Line 2:	701 5TH AVENUE, SUITE 6100
Address Line 4:	SEATTLE, WASHINGTON 98104-7043
ATTORNEY DOCKET NUMBER:	P248830.US.01
NAME OF SUBMITTER:	DENTON W. MCALISTER
SIGNATURE:	/Denton W. McAlister/
DATE SIGNED:	02/19/2015
Total Attachments: 3	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

SAMEER S. VADHAVKAR, XIAO LI, and
ANILKUMAR CHANDOLU

Docket No. P248830.US.01

Disclosure No. 2014-0451.00/US

Filed : Concurrently herewith

For : APPARATUSES AND METHODS
FOR SEMICONDUCTOR DIE HEAT
DISSIPATION

ASSIGNMENT :

 X Enclosed for recording

 Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**APPARATUSES AND METHODS FOR SEMICONDUCTOR DIE HEAT DISSIPATION**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Sameer S. Vadhavkar
SAMEER S. VADHAVKAR

Date: 2/18/2015

STATE OF IDAHO)
County of Ada) ss.

BEFORE ME, this 18th day of February, 2015, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her own free will for the purpose therein expressed.

SEAL



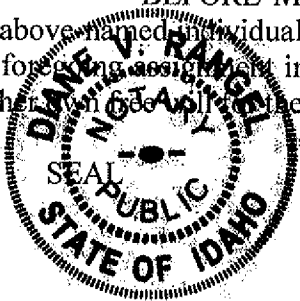
Diane V. Rangel
Notary or Consular Officer
My Commission Expires 6-30-17

Xiao Li
XIAO LI

Date: 2/18/2015

STATE OF IDAHO)
County of Ada) ss.

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Diane V. Rangell
Notary or Consular Officer
My Commission Expires 6-30-17

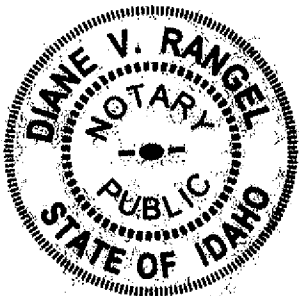
Ch. Anil Kumar
ANILKUMAR CHANDOLU

Date: 02/18/2015

STATE OF IDAHO)
County of Ada) ss.

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SEAL



Diane V. Rangell
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